



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
□	4	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
○	7	0.508mm (20.00mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c76h51
▽	7	2.700mm (106.30mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c270hn270
▣	24	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v50h30
	42 Total							

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.508mm	4.2	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				